General Description

The SJD30N018 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

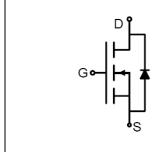
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- Load switch
- PWM applications
- Power management

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	30	V
R _{DS(ON)_TYP}	2	mΩ
I _D	145	А
Q _G	105	nC







Schematic Diagram

TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD30N018	SJD30N018	TO-252	Tape	\	\	2500 Pcs

Table 1. Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	30	V
Vgs	Gate-Source Voltage (V _{DS} =0V)	±20	V
1-	Drain Current-Continuous(Tc=25°C)	145	А
I _D	Drain Current-Continuous(Tc=100°C)	92	А
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	580	А
D-	Maximum Power Dissipation(Tc=25°C)	83	W
P _D	Maximum Power Dissipation(Tc=100°C)	33	W
Eas	Avalanche energy (Note 2)	625	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$ C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case		1.5	°C/W



Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

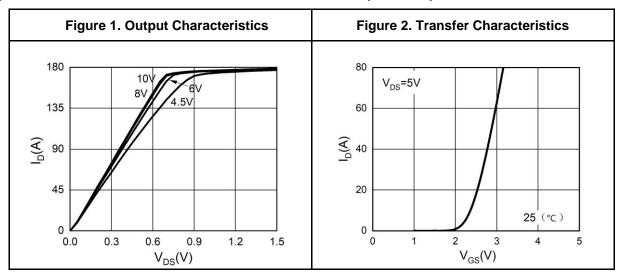
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
	7 0	V _{DS} =30V, V _{GS} =0V T _J =25°C			1	μA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =125℃			100	μA
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1.0		2.5	V
g FS	Forward Transconductance	V _{DS} =5V, I _D =20A		46		S
Б	Dunin Course On Otata Basistanas	V _{GS} =10V, I _D =20A T _J =25°C		2	2.5	mΩ
$R_{DS(ON)}$	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =20A T _J =25°C		3	4	mΩ
Dynamic Chara	acteristics		•	•	•	•
Ciss	Input Capacitance			6040		pF
Coss	Output Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		627		pF
C _{rss}	Reverse Transfer Capacitance			551		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		0.88		Ω
Switching Para	meters		•	•	•	•
t _{d(on)}	Turn-on Delay Time			13		nS
t _r	Turn-on Rise Time	V _{GS} =10V, V _{DS} =15V,		30		nS
t _{d(off)}	Turn-Off Delay Time	R _L =0.75Ω, R _{GEN} =3Ω		85		nS
t _f	Turn-Off Fall Time			50		nS
Q_g	Total Gate Charge			105		nC
Q_{gs}	Gate-Source Charge	V _{GS} =10V, V _{DS} =15V, I _D =20A		20		nC
Q_{gd}	Gate-Drain Charge			20		nC
Source-Drain D	Piode Characteristics		•	•	•	•
I _{SD}	Source-Drain Current (Body Diode)				145	А
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		28		ns
Qrr	Reverse Recovery Charge	I=20A, dI/dt=100A/μs		16		nC
		1				

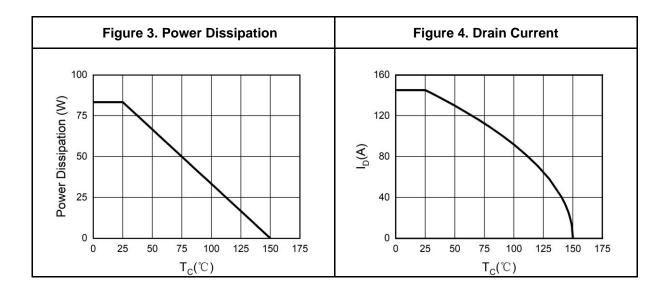
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

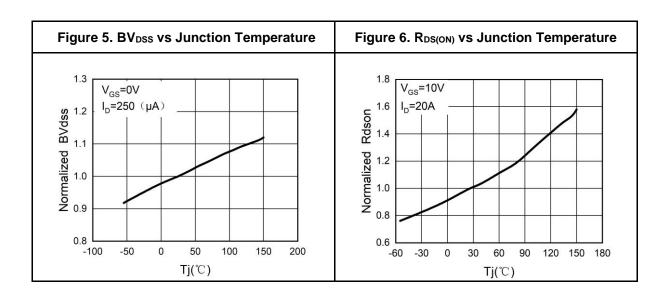
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=30V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

Notes 3. Repetitive Rating: Pulse width limited by maximum junction temperature.

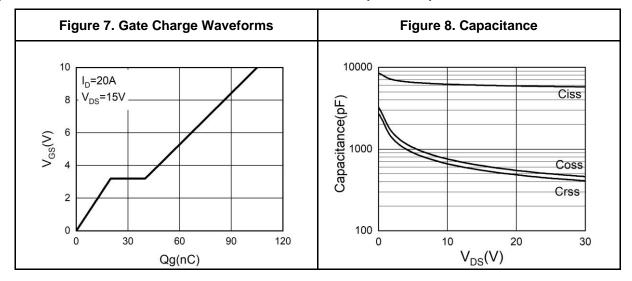
Typical Electrical And Thermal Characteristics (Curves)

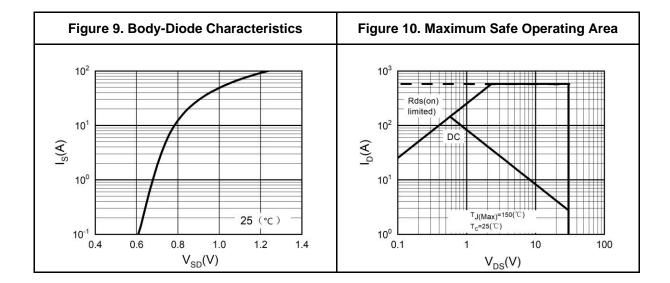






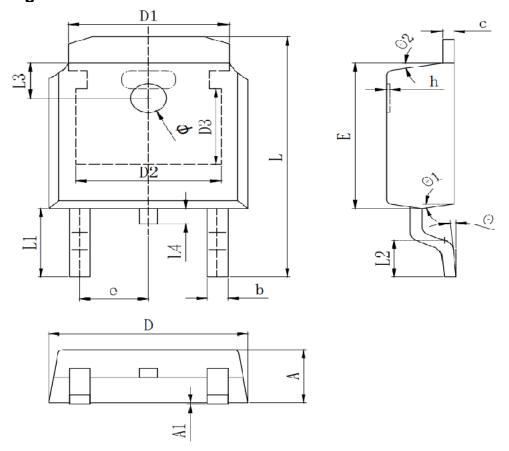
Typical Electrical And Thermal Characteristics (Curves)







TO-252 Package Information



Symbol	Dimensions In Millimeters				
Symbol	Min.	Тур.	Max.		
А	2.200	2.300	2.400		
A1	0.000		0.127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6.700		
D1		5.334 REF			
D2		4.826 REF			
D3		3.166 REF			
Е	6.000	6.100	6.200		
е		2.286 TYP			
h	0.000	0.100	0.200		
L	9.900	10.100	10.300		
L1		2.888 REF			
L2	1.400	1.550	1.700		
L3		1.600 REF			
L4	0.600	0.800	1.000		
Ф	1.100	1.200	1.300		
θ	0°		8°		
θ1		9° TYP			
θ2		9° TYP			



Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor

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